Table 1-1: Overview of the exemptions requested for renewal, associated recommendations and expiry dates

Ex. Req. No.	Requested exemption wording	Applicant/s	Recommendation	Expiry date & scope
Annex III, 6(a) and 6(a)-I	*"Lead as an alloying element in steel for machining purposes and in galvanised steel containing up to 0,35 % lead by weight." and "Lead as an alloying element in steel for machining purposes containing up to 0,35 % lead by weight and in batch hot dip galvanised steel components containing up to 0,2 % lead by weight"*	RÖHM GmbH; The Umbrella Project	6(a): Lead as an alloying element in steel for machining purposes containing up to 0,35 % lead by weight and in galvanized steel containing up to 0,35 % lead by weight	— 21 July 2023 for category 8 in vitro diagnostic medical devices; — 21 July 2024 for category 9 industrial monitoring and control instruments, and for category 11
			6(a)-I: Lead as an alloying element in steel for machining purposes containing up to 0,35 % lead by weight	Expires on 21 July 2024 for all categories
			6(a)-II: Lead in batch hot dip galvanised steel components containing up to 0,2 % lead by weight	Expires on 21 July 2026 for all categories
Annex III, 6(b)/6(b)-I	"*Lead as an alloying element in aluminium containing up to 0,4 % lead by weight*" and "*Lead as an alloying element in aluminium containing up to 0,4 % lead by weight, provided it stems from lead-bearing aluminium scrap recycling*"	European Aluminium; The Umbrella Project	6(b)-I: Lead as an alloying element in aluminium containing up to 0,4% lead by weight provided it stems from lead-bearing aluminium scrap recycling	Expires 12 months after the decision for all categories
			6(b)-III: Lead as an alloying element in aluminium casting alloys containing up to 0,3% lead by weight provided it stems from lead-bearing aluminium scrap recycling	Expires on 21 July 2026 for all categories

Ex. Req. No.	Requested exemption wording	Applicant/s	Recommendation	Expiry date & scope
Annex III, 6(b)-II	*"Lead as an alloying element in aluminium for machining purposes with a lead content up to 0,4 % by weight"*	The Umbrella Project	6(b)-II: Lead as an alloying element in aluminium for machining purposes with a lead content up to 0,4 % by weight.	Expires 18 months after the decision for all categories
			6(b)-IV: Lead as an alloying element in aluminium for machining purposes with a lead content up to 0,4 % by weight in gas valves applied in category 1 EEE (large household appliances)	Expires on 31 December 2024
Annex III, 6(c)	*"Copper alloy containing up to 4 % lead by weight"*	Bourns Inc.; The Umbrella Project	6(c): Copper alloy containing up to 4 % lead by weight	Expires on 21 July 2026 for all categories
Annex III, 7(a)	*"Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)"*	Bourns Inc.; The Umbrella Project	Lead in high melting temperature type solders (i.e., lead-based alloys containing 85 % by weight or more lead) (excludes those in the scope of exemption 24)	For all categories except applications covered by point 24 of this Annex, expires on 21 July 2024.
			Lead in high melting temperature type solders (i.e., lead-based alloys containing 85 % by weight or more lead) when used for the following applications (excludes those in the scope of exemption 24): I) for internal interconnections for attaching die, or other components along with a die in semiconductor assembly with steady state or transient/impulse currents of 0.1 A or greater or blocking voltages beyond 10 V, or die edge sizes larger than 0.3 mm x 0.3 mm II) for integral (meaning internal and external) connections of die attach in electrical and electronic components, if the thermal conductivity of the cured/sintered die-attach material is >35W/(m*K) AND the electrical conductivity of the cured/sintered die-attach material shall be >4.7MS/m AND solidus melting temperature has to be above 260°C	Applies to all categories except applications covered by point 24 of this Annex, expires on 21 July 2026

Ex. Req. No.	Requested exemption wording	Applicant/s	Recommendation	Expiry date & scope
			III) In first level solder joints (internal or integral connections - meaning internal and external) for manufacturing components so that subsequent mounting of electronic components onto subassemblies (i.e., modules or sub-circuit boards or substrates or point to point soldering) with a secondary solder does not reflow the first level solder. This item excludes die attach applications and hermetic sealings IV) In second level solder joints for the attachment of components to printed circuit board or lead frames: 1. in solder balls for the attachment of ceramic ball-grid-array (BGA) 2. in high temperature plastic overmouldings (> 220 °C) V) as a hermetic sealing material between: 1. a ceramic package or plug and a metal case, 2. component terminations and an internal sub-part VI) for establishing electrical connections between lamp components in incandescent reflector lamps for infrared heating or high intensity discharge lamps or oven lamps VII) for audio transducers where the peak operating temperature exceeds 200°C	

Ex. Req. No.	Requested exemption wording	Applicant/s	Recommendation	Expiry date & scope
Annex III, 7(c)-I	*"Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in ca-pacitors, e.g. piezoelec-tronic devices, or in a glass or ceramic matrix compound"*	COCIR; SCHOTT AG; Bourns Inc.; Photonis Scientific, Inc.; Optical Fiber Packaging Ltd; The Umbrella Project	7(c)-I: Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezo-electronic devices, or in a glass or ceramic matrix compound	Expires on 21 July 2024 for all categories
			7(c)-V: Electrical and electronic components containing lead in a glass or glass matrix compound that fulfils the following functions: 1) protection and electrical insulation in glass beads of high voltage diodes and glass layers for wafer on the basis of a lead-zinc-borate or a lead-silica-borate glass body,* 2) for hermetic sealings between ceramic, metal and/or glass parts 3) for bonding purposes in a process parameter window for < 500°C combined with a viscosity of $10^{13,3}$ dPas (so called "glass-transition temperature") 4) used as resistance materials such as ink, with a resistivity range from 1 Ohms/square to 1 Mega Ohms/square, excluding trimmer potentiometers** 5) used in chemically modified glass surfaces for Microchannel Plates (MCPs), Channel Electron Multipliers (CEMs) and Resistive Glass Products (RGPs).	Expires on 21 July 2026 for all categories
			7(c)-VI: Electrical and electronic components containing lead in a ceramic that fulfils the following functions (excluding items covered under item 7(c)-II, 7(c)-III and 7(c)-IV of this annex): 1) piezoelectric lead zirconium titanate (PZT) ceramics 2) providing ceramics with a positive temperature coefficient (PTC)	Expires on 21 July 2026 for all categories
Annex III, 7(c)-II	*"Lead in dielectric ceramic in capacitors for a rated volt-age of 125 V AC or 250 V DC or higher"*	The Umbrella Project	7(c)-II: Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher	Does not apply to applications covered by point 7(c)-I and 7(c)-IV of this Annex. Expires on 21 July 2026 for all categories

Note: As in the RoHS legal text, commas are used as a decimal separator for exemption formulations appearing in this table, in contrast to the decimal point used throughout the rest of the report as a separator